

Product: souufloogf

Total Carbon Footprint

70.05 kgCO2e

Carbon Intensity

70.05 kgCO2e/unit

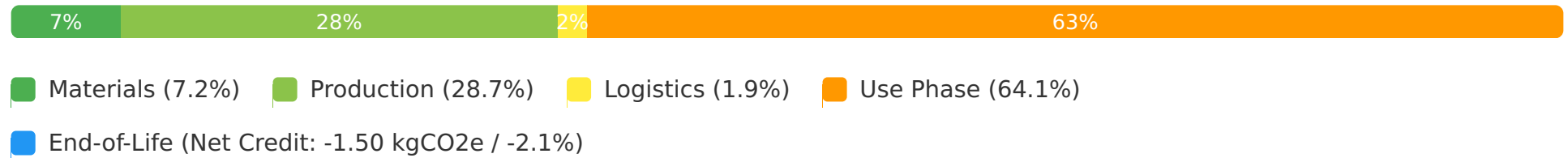
Top Material Hotspot

PCB (1.80 kgCO2e)

Primary Emission Scope

Use Phase (64.1%)

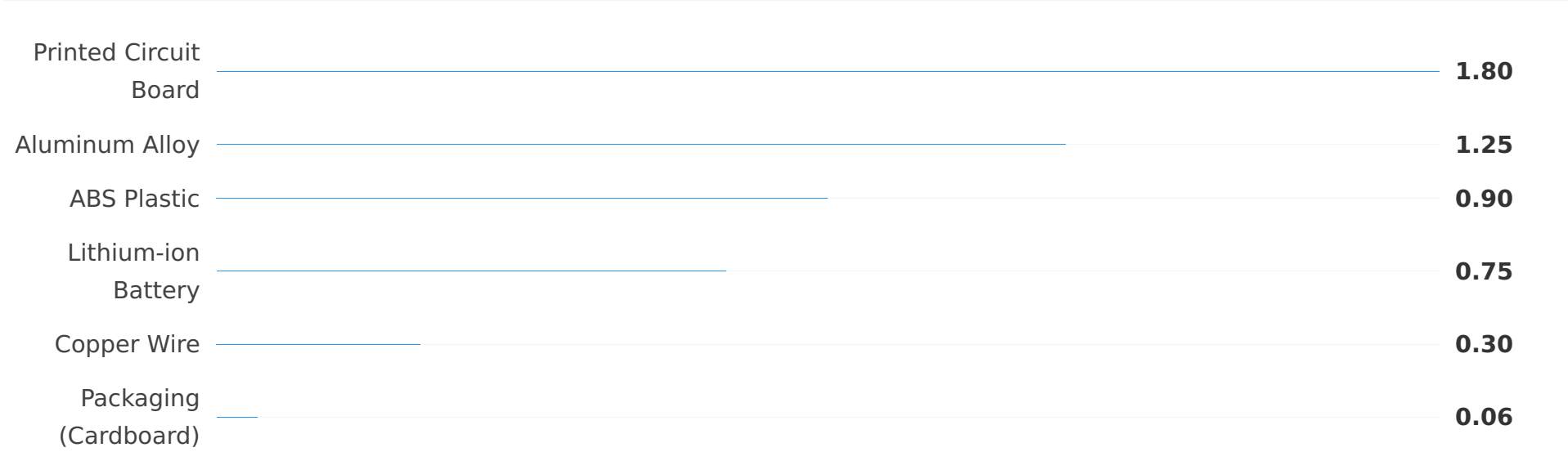
Emissions Breakdown by Lifecycle Stage



Key Insights & Hotspots

- The **Use Phase** is the dominant emission hotspot, contributing 64.1% of the total carbon footprint. This is primarily due to energy consumption during the product's operational lifespan.
- **Scope 1 Direct Emissions** (on-site fuel combustion for manufacturing) represent a significant 28.5% of the total, indicating substantial opportunities for decarbonization within production facilities.
- **Purchased Goods & Services (Materials)** account for 7.2%, with the Printed Circuit Board (PCB) identified as a key material impact area (1.80 kgCO2e).

Top Material Carbon Impacts (kgCO2e)



Recommendations & Action Plan

- **Prioritize Use Phase Optimization:** Design 'souffloof' for maximum energy efficiency, explore low-power modes, and educate users on sustainable usage.
- **Decarbonize Production Facilities:** Invest in renewable energy sources for Scope 1 and Scope 2 emissions at manufacturing sites.
- **Enhance Material Circularity:** Increase recycled and sustainably sourced materials in the Bill of Materials and expand take-back programs.
- **Optimize Logistics:** Evaluate opportunities to optimize transportation routes and shift to lower-emission transport modes.
- **Data Refinement:** Collect more granular and specific primary data for all parameters to continuously improve future PCF assessments.

Report generated by carboncalcpcf.com adhering to GHG Protocol & 2026 LSR standards. The GHG Protocol's Land Sector and Removals (LSR) Standard was released on January 30, 2026, and is set to take effect on January 1, 2027.

Disclaimer: This dashboard provides a summary of illustrative data. Precise calculations require verified primary data.